

Delivering Value through Innovation and Dedication











# ThunderClad 2A

Core: TU-883A Prepreg: TU-883PA

ThunderClad 2A (TU-883A) is a very low loss category material based on a high performance modified FR-4 resin. This material is reinforced with regular woven E-glass and designed with very low dielectric constant and dissipation factor resin system for high speed low loss, radio frequency and wireless applications. ThunderClad 2A material is suitable for environmental protection lead free process and also compatible with FR-4 processes. ThunderClad 2A laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability and CAF resistance.

## **Applications**

- Radio frequency
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

## Performance and Processing Advantages

- Excellent electrical properties
- Dielectric constant less than 3.89
- Dissipation factor less than 0.0040
- Stable and flat Dk/Df performance over frequency and temperature
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Anti-CAF capability
- Excellent through-hole and soldering reliability
- Halogen Free

## **Industry Approvals**

UL File Number: E189572
ANSI Grade: No-ANSI
Flammability Rating: 94V-0

Maximum Operating Temperature: 160°C

## Standard Availability

- Thickness: 0.002"[0.05mm] to 0.030" [0.76mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 2 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 106, 1078, 3313, 2116 and other prepreg grades are available upon request





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Typical Properties			
	Typical Values	Test Condition	SPEC
Thermal			
Tg (DMA) Tg (TMA) Td (TGA)	210 °C 170 °C 410 °C	E-2/105+des	N/A
CTE z–axis α1 CTE z–axis α2 CTE z–axis	30 ppm/°C 230 ppm/°C 2.3 %	Pre-Tg Post-Tg 50 to 260°C	< 60 ppm/°C < 300 ppm/°C < 3.0%
Thermal Stress, Solder Float, 288°C	> 60 sec	A	> 10 sec
T-260 T-288 T-300	> 60 min > 60 min > 60 min	E-2/105+des	> 30 min > 15 min
Flammability	94V-0	E-24/125+des	94V-0
Electrical			
Permittivity (RC63%) 1GHz (SPC method) 5GHz (SPC method) 10GHz (SPC method)	3.67 3.66 3.64	C-24/23/50	N/A
Loss Tangent (RC63%) 1GHz (SPC method) 5GHz (SPC method) 10GHz (SPC method)	0.0020 0.0027 0.0036	C-24/23/50	N/A
Volume Resistivity	> 10¹º MΩ∙cm	C-96/35/90	$> 10^6\mathrm{M}\Omega\cdot\mathrm{cm}$
Surface Resistivity	$> 10^8  \text{M}\Omega$	C-96/35/90	$> 10^4\text{M}\Omega$
Electric Strength	> 40 KV/mm	-	> 30 KV/mm
Dielectric Breakdown Voltage	> 50 KV		> 40 KV
Mechanical			
Young's Modulus Warp Direction Fill Direction	31 GPa 29 GPa	A	N/A
Flexural Strength Lengthwise Crosswise	> 60,000 psi > 50,000 psi	A A	> 60,000 psi > 50,000 psi
Peel Strength, 1.0 oz. Cu foil	4~6 lb/in	A	> 4 lb/in
Water Absorption	0.08 %	E-1/105+des+D-24/23	< 0.8 %

#### NOTE:

- $1.\ Property\ values\ are\ for\ information\ purposes\ only\ and\ not\ intended\ for\ specification.$
- 2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
- 3. This product is based on a patent pending technology.

